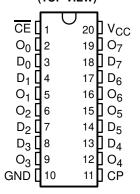
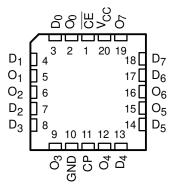
- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Fully Compatible With TTL Input and Output Logic Levels
- Clock Enable for Address and Data Synchronization Application
- Eight Edge-Triggered D-Type Flip-Flops
- CY54FCT377T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT377T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

SN74FCT377T . . . Q OR SO PACKAGE (TOP VIEW)



SN54FCT377T . . . L PACKAGE (TOP VIEW)



description

The 'FCT377T devices have eight triggered D-type flip-flops with individual data (D) inputs. The common buffered clock (CP) inputs load all flip-flops simultaneously when the clock-enable ($\overline{\text{CE}}$) input is low. The register is fully edge triggered. The state of each D input at one setup time before the low-to-high clock transition is transferred to the corresponding flip-flop output (O). $\overline{\text{CE}}$ must be stable only one setup time prior to the low-to-high clock transition for predictable operation.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

TA	PAC	KAGET	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QSOP – Q	Tape and reel	5.2	CY74FCT377CTQCT	FCT377C
	SOIC - SO	Tube	5.2	CY74FCT377CTSOC	FCT377C
–40°C to 85°C	3010 = 30	Tape and reel	5.2	CY74FCT377CTSOCT	1013770
	QSOP – Q	Tape and reel	7.2	CY74FCT377ATQCT	FCT377A
	SOIC - SO	Tube	7.2	CY74FCT377ATSOC	FCT377A
	3010 - 30	Tape and reel	7.2	CY74FCT377ATSOCT	FC13//A
QSOP – C		Tape and reel	13	CY74FCT377TQCT	FCT377
–55°C to 125°C	LCC – L	Tube	5.5	CY54FCT377CTLMB	
-55 C to 125°C	LOG – L	Tube	8.3	CY54FCT377ATLMB	

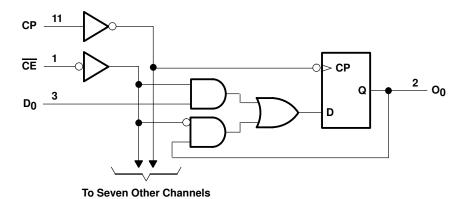
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS		OUTPUT	OPERATING
СР	CE	D	0	MODE
1	I	h	Н	Load 1
1	I	1	L	Load 0
↑ X	h H	X X	No change	Hold

 $H=High\,logic\,level,\,h=High\,logic\,level\,one$ setup time prior to the low-to-high clock transition, $L=Low\,logic\,level,\,l=Low\,logic\,level$ one setup time prior to the low-to-high clock transition, $X=Don't\,care,\,\uparrow=Low-to-high\,clock\,transition$

logic diagram



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	0.5 V to 7 V
DC input voltage range	0.5 V to 7 V
DC output voltage range	0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	-65° C to 150° C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 2)

		CY54FCT377T		7T	CY7	74FCT37	7T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			8.0			0.8	V
ІОН	High-level output current			-12			-32	mA
loL	Low-level output current			32			64	mA
T _A	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

SCCS023A - MAY 1994 - REVISED OCTOBER 2001

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BABAMETER			NO	CY	54FCT37	7T	CY	74FCT37	7T	
PARAMETER	16	EST CONDITIO	NS	MIN	түр†	MAX	MIN	түр†	MAX	UNIT
V	$V_{CC} = 4.5 \text{ V}, I_{IN}$	_V = −18 mA			-0.7	-1.2				V
VIK	V _{CC} = 4.75 V, I _{IN}	_V = −18 mA						-0.7	-1.2	V
	$V_{CC} = 4.5 \text{ V}, \qquad I_{O}$)H = −12 mA		2.4	3.3					
Voн	V _{CC} = 4.75 V	_{)H} = –32 mA					2			V
	VCC = 4.75 V)H = -15 mA					2.4	3.3		
Vol	$V_{CC} = 4.5 \text{ V}, \qquad I_{O}$)L = 32 mA			0.3	0.55				V
V _{OL}	V _{CC} = 4.75 V, I _O	_{DL} = 64 mA						0.3	0.55	V
V _{hys}	All inputs				0.2			0.2		V
1.	$V_{CC} = 5.5 \text{ V}, \qquad V_{I}$	IN = ACC				5				μΑ
lį	$V_{CC} = 5.25 \text{ V}, V_{I}$	IN = VCC							5	μΑ
ΊΗ	$V_{CC} = 5.5 \text{ V}, \qquad V_{I}$	_{IN} = 2.7 V				±1				μΑ
ЧН	$V_{CC} = 5.25 \text{ V}, V_I$	IN = 2.7 V							±1	μΑ
lu	$V_{CC} = 5.5 \text{ V}, \qquad V_{I}$	IN = 0.5 V				±1				μΑ
IIL	$V_{CC} = 5.25 \text{ V}, V_I$	IN = 0.5 V							±1	μΑ
1+	$V_{CC} = 5.5 \text{ V}, \qquad V_{C}$	OUT = 0 V		-60	-120	-225				mA
l _{OS} ‡	$V_{CC} = 5.25 \text{ V}, V_{C}$	OUT = 0 V					-60	-120	-225	ША
l _{off}	$V_{CC} = 0 V, V_C$	OUT = 4.5 V				±1			±1	μΑ
loo	$V_{CC} = 5.5 \text{ V}, \qquad V_{I}$	IN ≤ 0.2 V,	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA
lcc	$V_{CC} = 5.25 \text{ V}, V_I$	• •						0.1	0.2	шА
Δl _{CC}	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3$	•			0.5	2				mA
∆i()(i	V _{CC} = 5.25 V, V _{IN} =	$= 3.4 \text{ V}$, $f_1 = 0$,	Outputs open					0.5	2	шл

 $[\]overline{\text{T}}$ Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

 $[\]$ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		TECT COMPLETO	NO	С	54FCT37	7T	CY	74FCT37	7T	LIAUT
PARAMETER		TEST CONDITIO	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT	
ICCD¶		itputs open, g at 50% duty cycle $IN \ge V_{CC} - 0.2 V$, CE = GND,		0.06	0.12				mA/
		outputs open, g at 50% duty cycle $IN \ge V_{CC} - 0.2 V$					0.06	0.12	MHz	
		One bit switching at f ₁ = 5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	V _{CC} = 5.5 V, Outputs open,	50% duty cycle	V _{IN} = 3.4 V or GND		1.2	3.4				
	f ₀ = 10 MHz, CE = GND	Eight bits switching at f ₁ = 2.5 MHz at	$\begin{aligned} V_{IN} &\leq 0.2 \text{ V or} \\ V_{IN} &\geq V_{CC} - 0.2 \text{ V} \end{aligned}$		1.6	3.2				
I _C #		50% duty cycle	V _{IN} = 3.4 V or GND		3.9	12.2				A
IC"		One bit switching at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	mA
	V _{CC} = 5.25 V, Outputs open,	f ₁ = 5 MHz at 50% duty cycle	V _{IN} = 3.4 V or GND					1.2	3.4	
	$\frac{f_0}{CE} = 10 \text{ MHz},$ CE = GND	Eight bits switching at f ₁ = 2.5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1.6	3.2	
		50% duty cycle	V _{IN} = 3.4 V or GND					3.9	12.2	
C _i	_		_		5	10		5	10	pF
Co					9	12		9	12	pF

[†] Typical values are at V_{CC} = 5 V, T_A = 25°C.

Where:

I_C = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

 \dot{N}_1 = Number of inputs changing at f_1

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



This parameter is derived for use in total power-supply calculations.

 $^{\#} I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

CY54FCT377T, CY74FCT377T 8-BIT REGISTERS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY54FCT CY54FCT	-	CY74FCT CY74FCT CY74FCT	377AT	UNIT
			MIN	MAX	MIN	MAX	
t _W	Pulse duration, CP high or low [†]		7		6		ns
	Setup time, high or low	Data before CP↑			2		
t _{su}	Setup time, high or low	CE before CP↑	3.5		3.5		ns
.	Hold time, high or low	Data after CP↑	1.5		1.5		
th	Hold tille, high or low	CE after CP↑	1.5		1.5		ns

[†] With one data channel switching, $t_{W(L)} = t_{W(H)} = 4$ ns and $t_r = t_f = 1$ ns.

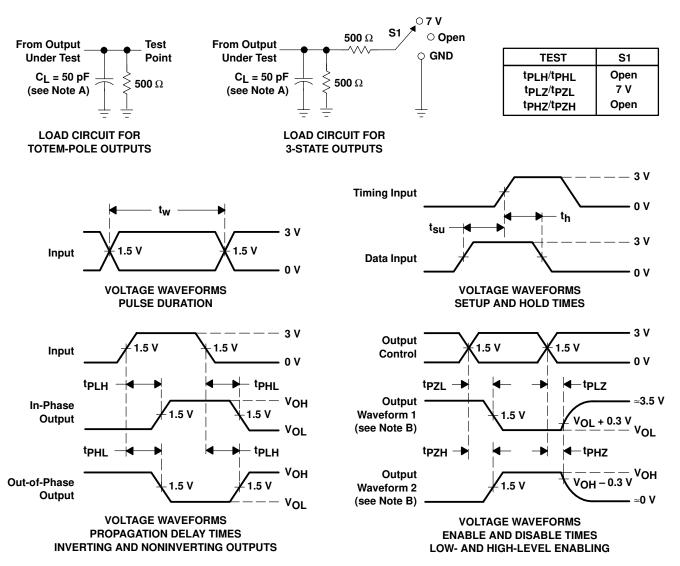
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM		PARAMETER FROM TO		CY54FC	Г377АТ	CY54FC	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT	
^t PLH	СР	0	2	8.3	2	5.5		
^t PHL	OF .	U	2	8.3	2	5.5	ns	

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FC	T377T	CY74FC	377AT	CY74FC1	T377CT	UNIT
PANAMETEN	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	СР	0	2	13	2	7.2	2	5.2	no
^t PHL	GF	O	2	13	2	7.2	2	5.2	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9221902M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9221902M2A	Samples
5962-9221903M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9221903M2A CY54FCT 377CTLMB	Samples
CY54FCT377CTLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9221903M2A CY54FCT 377CTLMB	Samples
CY74FCT377ATQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT377A	Samples
CY74FCT377ATSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT377A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

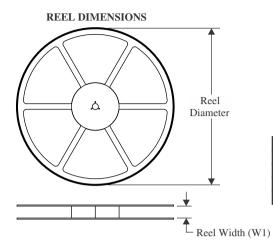
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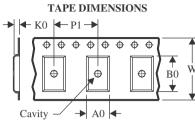
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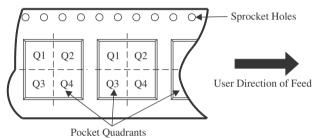
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

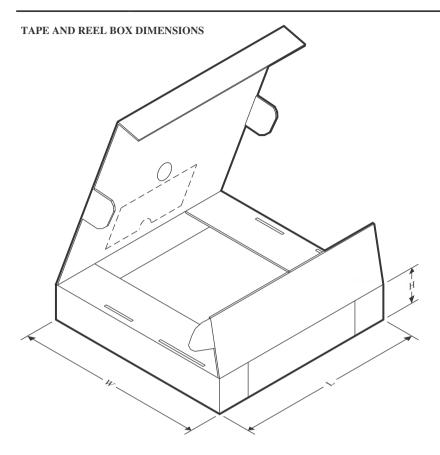


*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT377ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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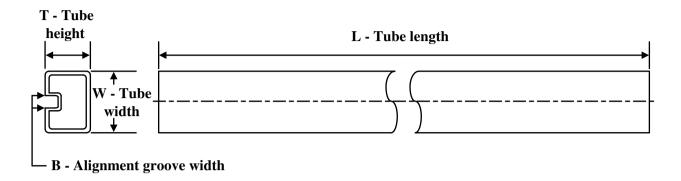
*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	CY74FCT377ATQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9221902M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-9221903M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT377CTLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY74FCT377ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6

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